

IN THE CLAIMS

Please amend the claims as follows:

Claim 1 (currently amended): A ceramic heater for heating a semiconductor wafer, comprising:

a ceramic substrate ~~in a disc form and~~ having a first surface and a second surface;

a resistance heating element formed on the second surface of said ceramic substrate or inside said ceramic substrate, and including at least two circuits;

~~wherein: said ceramic heater is equipped with:~~

[[a]] temperature-measuring means for measuring the temperature of said ceramic substrate or an object to be heated;

a control unit ~~supplying~~ configured to supply electric power to said heating element;

a memory unit ~~memorizing~~ configured to store the temperature data measured by said temperature-measuring means; and

an operation unit ~~calculating~~ configured to calculate, based on said temperature data, electric power data required for said heating element from said temperature data, said ceramic heater being constituted such that said heating element is divided into at least 2 or more circuits and to attain a uniform temperature of the first surface,

wherein different electric power is supplied to each of the at least two circuits based on the calculated electric power data.

Claim 2 (currently amended): A ceramic heater for heating a semiconductor wafer, comprising:

a ceramic substrate ~~in a disc form and~~ having a first surface and a second surface;

a resistance heating element formed on the second surface of said ceramic substrate or inside said ceramic substrate, and including at least two circuits;

~~wherein: said ceramic heater is equipped with:~~

[[a]] temperature-measuring means for measuring the temperature of said ceramic substrate or an object to be heated;

a power source ~~supplying~~ configured to supply electric power to said heating element;

a control unit ~~controlling~~ configured to control the power source;

a memory unit ~~memorizing~~ configured to store the temperature data measured by said temperature-measuring means; and

~~an operation unit~~ means for calculating, based on said temperature data, electric power data required for said heating element ~~from said temperature data; said ceramic heater being constituted such that said heating element is divided into at least 2 or more circuits and~~ to attain a uniform temperature of the first surface,

wherein different electric power is supplied to each of the at least two circuits based on the calculated electric power data.

Claim 3 (currently amended): The ceramic heater for heating a semiconductor wafer according to claim 1, wherein said temperature-measuring means [[is]] comprises a temperature-measuring element.

Claim 4 (currently amended): The ceramic heater for heating a semiconductor wafer according to claim 1, wherein said temperature-measuring means [[is]] comprises a thermoviewer.

Claim 5 (currently amended): The ceramic heater for heating a semiconductor wafer according to claim 2, wherein said temperature-measuring means [[is]] comprises a temperature-measuring element.

Claim 6 (currently amended): The ceramic heater for heating a semiconductor wafer according to claim 2, wherein said temperature-measuring means [[is]] comprises a thermoviewer.

Claim 7 (new): The ceramic heater for heating a semiconductor wafer according to claim 1, wherein said ceramic substrate comprises a nitride ceramic or a carbide ceramic.

Claim 8 (new): The ceramic heater for heating a semiconductor wafer according to claim 1, wherein said temperature-measuring means comprises a thermocouple.

Claim 9 (new): The ceramic heater for heating a semiconductor wafer according to claim 1, wherein said ceramic heater comprises plural temperature-measuring means.

Claim 10 (new): The ceramic heater for heating a semiconductor wafer according to claim 2, wherein said ceramic substrate comprises a nitride ceramic or a carbide ceramic.

Claim 11 (new): The ceramic heater for heating a semiconductor wafer according to claim 2, wherein said temperature-measuring means comprises a thermocouple.

Claim 12 (new): The ceramic heater for heating a semiconductor wafer according to claim 2, wherein said ceramic heater comprises plural temperature-measuring means.